

# Super Series FPC Materials / Super Flexible Copper Clad

## Excellent Dimension Stability and Precision due to Glass Cloth Base

### Features and Benefits

- Excellent Heat Resistance.
- Powder Free in Punching Process.
- Production Capacity max 200k sq-meter/month
- Stable Characteristic due to less Effect of Moisture Absorption
- Roll supply is possible.
- Halogen Antimony Free

### Applications

- Flat Panel Display (LCD, PDP)
- Flex-Rigid for Digital Camera and Cellular Phone
- Powder Free Rigid Board for Camera Module and Microphone

Item	General Property		TLF-W-970		
			0.030	0.045	0.060
Insulation Thickness		Mm	0.030	0.045	0.060
Insulation Resistance (L/S=1.0/1.0mm)	A	ohm	$3.0 \times 10^{13} \sim 3.0 \times 10^{14}$		
	D-2/100		$1.0 \times 10^{13} \sim 1.5 \times 10^{14}$		
Permittivity	1GHz	-	3.8 ~ 4.1		
Dissipation Factor	1GHz	-	0.014 ~ 0.018		
Dimension Stability	MD	%	<0.02	<0.02	<0.02
	TD	%	<0.02	<0.01	<0.01
Peel Strength (ED)	18 μ m	KN/m	1.30		
Folding Endurance (MIT Method)	0.5N 135deg.	Cycle	>150	>100	>20
Tg (DMA)		C	140		

